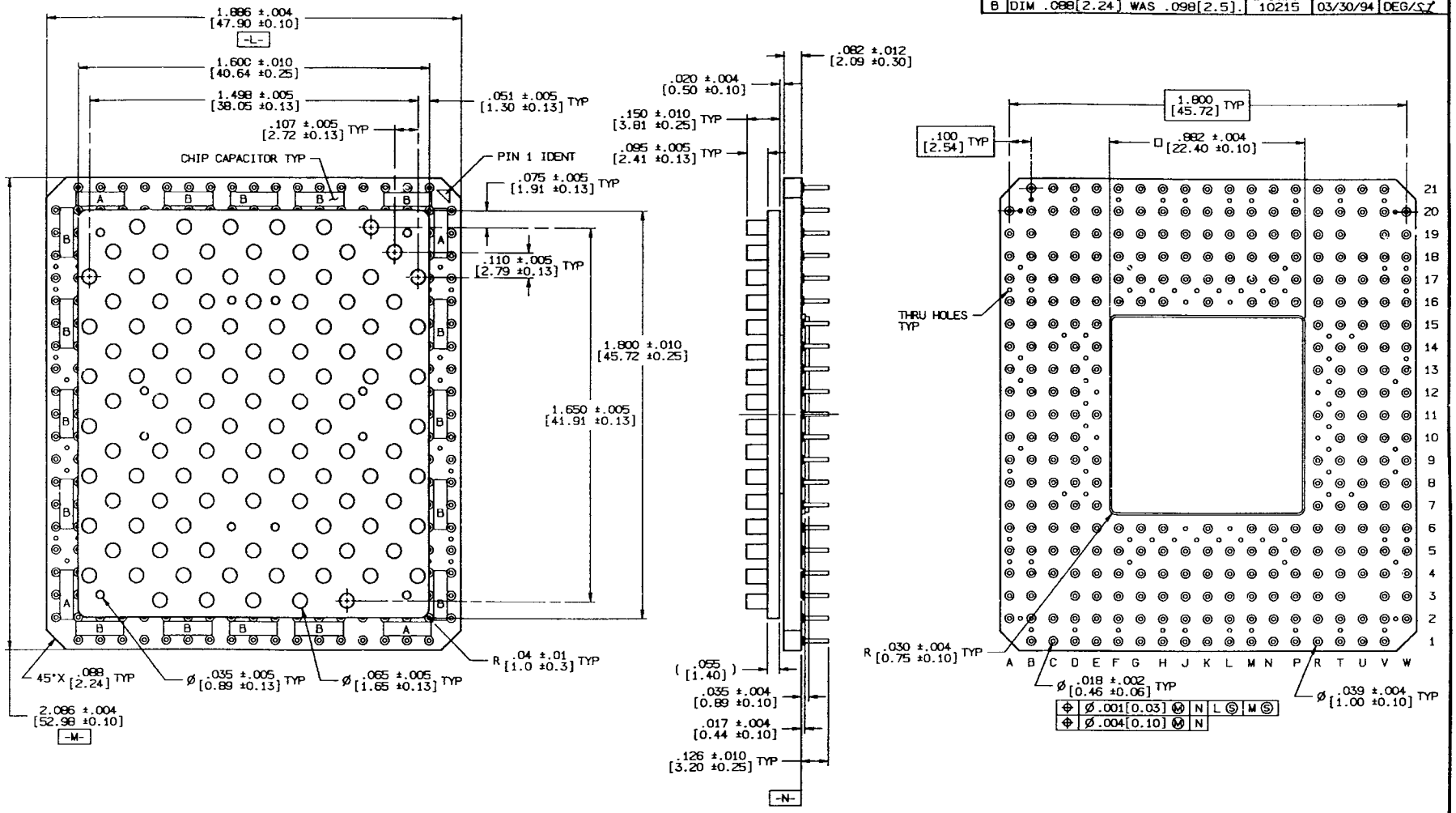
REVISIONS				
LTR	DESCRIPTION	E.C.N.	DATE	BY/APP'D
A	RELEASE TO DOCUMENT CONTROL	09962	09/08/93	KES/SL
B	DIM .088[2.24] WAS .098[2.5].	10215	03/30/94	DEG/SL



NOTES: UNLESS OTHERWISE SPECIFIED

1. ALL EXPOSED METAL AND METALIZED AREAS TO BE GOLD PLATED 20 MICROINCHES/0.5 MICROMETERS MINIMUM OVER 200 MICROINCHES/ 5.08 MICROMETERS MINIMUM OF NICKEL.
2. HEAT SINK MATERIAL: ZINC ALLOY (ASTM AG40A), BLACK FINISH.
3. NO JEDEC REGISTRATION AS OF 09-08-93.

CONTROLLING DIMENSION: MILLIMETER

APPROVALS	DATE
DRAWN Kurt Stacenko	09/08/93
DESIG. CHK. Thanh Lequang	4/12/94
ENGR'G CHK. Shoelke	4/15/94
APPROVAL	

NATIONAL SEMICONDUCTOR CORPORATION
2900 Semiconductor Drive, Santa Clara, CA 95052-8090

PIN GRID ARRAY, PLASTIC, 302 PIN

PROJECTION INCH [MM]

SCALE	SIZE	DRAWING NUMBER	REV
N/A	C	MKT-UP302A	B

DO NOT SCALE DRAWING — SHEET 1 OF 1